

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Sang-Geun Kim, Seung-Chul Ahn  
Assignee: Samsung Electronics Co., Ltd  
Title: Die Bonding Equipment (As Amended)  
Serial No.: Unknown Filing Date: August 6, 2001  
Examiner: Unknown Group Art Unit: Unknown  
Docket No.: **AB-878-1D US**

San Jose, California  
August 6, 2001

BOX NON-FEE AMENDMENT  
COMMISSIONER FOR PATENTS  
WASHINGTON, D. C. 20231

REQUEST TO AMEND DRAWINGS  
UNDER 37 C.F.R. § 1.121

Sir:

Pursuant to 37 C.F.R. §1.121, Applicants respectfully request permission to amend  
FIG. 6B as shown in red ink on the accompanying sheet.

Should the Examiner have any questions concerning this request, the Examiner is  
invited to call the undersigned at (408) 453-9200.

**Express Mail Label No.**

**EL 699 358 013 US**

**August 6, 2001**

Respectfully submitted,



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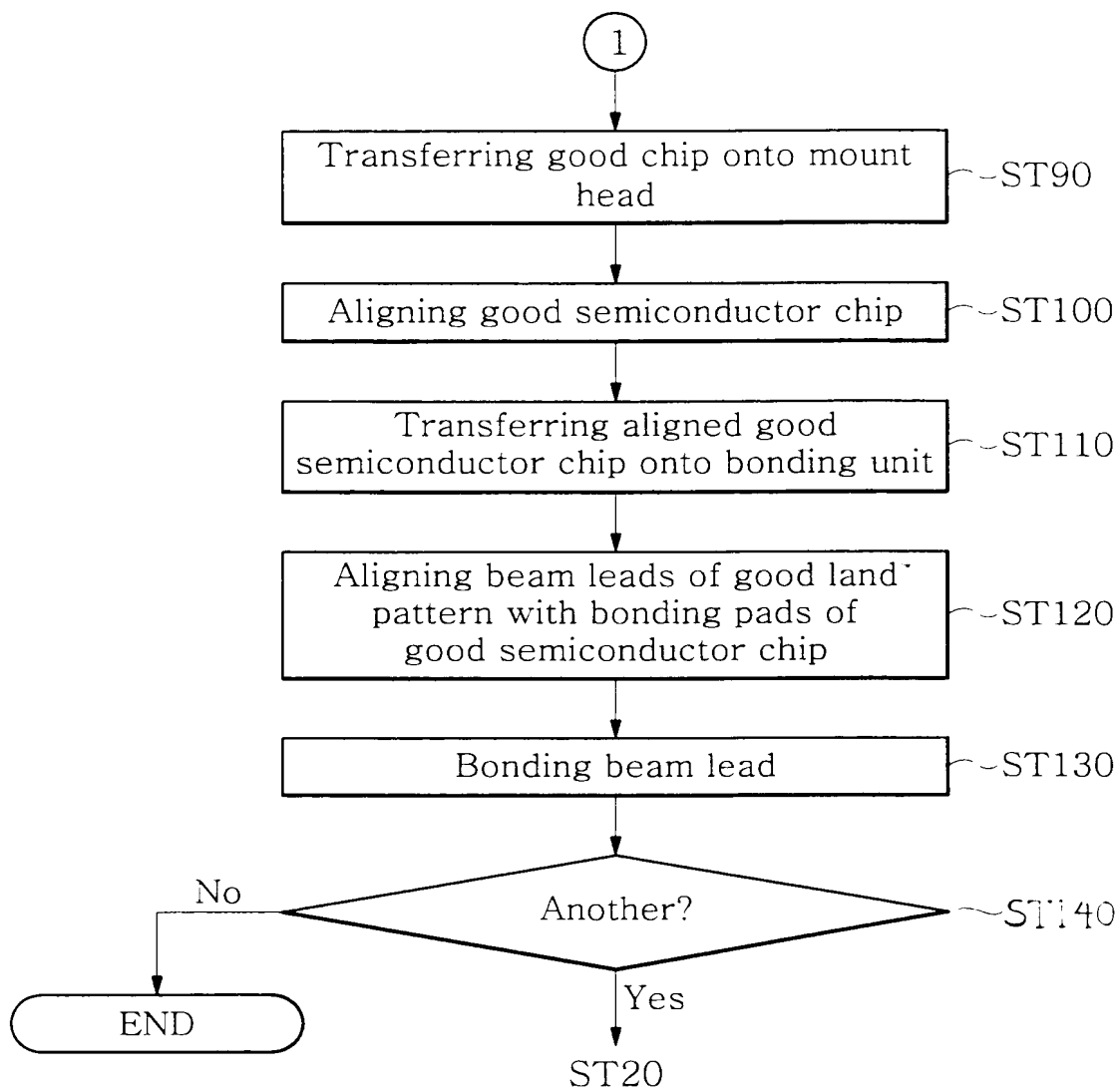


FIG. 6B